

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ018NE2LSI	**Issued**	11. May 2021
MA#	MA001651886		
Package	PG-TSDSON-8-26	**Weight***	36.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	1.82	1.82	18240	18240
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		267	
	non noble metal	iron	7439-89-6	0.197	0.53		5348	
	non noble metal	copper	7440-50-8	7.988	21.71	22.28	217139	222821
wire	noble metal	gold	7440-57-5	0.034	0.09	0.09	926	926
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		999	
	plastics	epoxy resin	-	1.893	5.15		51460	
	inorganic material	silicondioxide	60676-86-0	16.450	44.73	49.98	447150	499609
leadfinish	non noble metal	tin	7440-31-5	0.395	1.07	1.07	10744	10744
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	552	552
solder	non noble metal	tin	7440-31-5	0.019	0.05		519	
	noble metal	silver	7440-22-4	0.024	0.06		649	
	non noble metal	lead	7439-92-1	0.912	2.48	2.59	24793	25961
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2555	
	non noble metal	copper	7440-50-8	3.816	10.37	10.64	103724	106439
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001			34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2753	
	non noble metal	copper	7440-50-8	4.112	11.18	11.47	111783	114708
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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